

Technical specifications

Sl.No	Description of the Item
1.	<p>Material: Single part Electrically Conductive Epoxy</p> <p>Physical Form: Paste</p> <p>The Epoxy is used in Low bleed and low outgassing space applications.</p> <p>Application: Microelectronic die (Si & GaAs) attachment</p> <p>Filler material of the Epoxy: Silver</p> <p>Cure: Heat cure</p>
2.	Thermal Conductivity: ≥ 2.4 W/mK
3.	Shelf Life: ≥ 1 year. Storage conditions to be specified by the manufacturer.
4.	<p>Ionic Content, ppm:</p> <p>Chloride (Cl⁻): ≤ 20</p> <p>Sodium (Na⁺): ≤ 20</p> <p>Potassium(K⁺): ≤ 10</p>
5.	Volume resistivity: ≤ 0.0005 ohms-cm
6.	Quantity: 06 Cubic Centimeter material. 6 containers with 1 Cubic Centimeter material each.
7.	Data sheet to be provided along with quotation. Data sheet should contain typical material properties values like Viscosity, Thixotropic Index, Coefficient of thermal Expansion, Glass Transition Temperature, work life, shelf life, curing schedule etc.
8.	The material should have space heritage. Vendor to provide previous customers for space usage.
9.	If the material storage demands $< 25^{\circ}\text{C}$, it should be supplied with cold pack/dry ice packing.
10.	Shelf life of the material should be minimum 9 months at the time of delivery to URSC.
11.	The material should meet the requirements of MIL-STD.883, Method-5011. Certificate of Conformance (COC) to be provided along with Material.